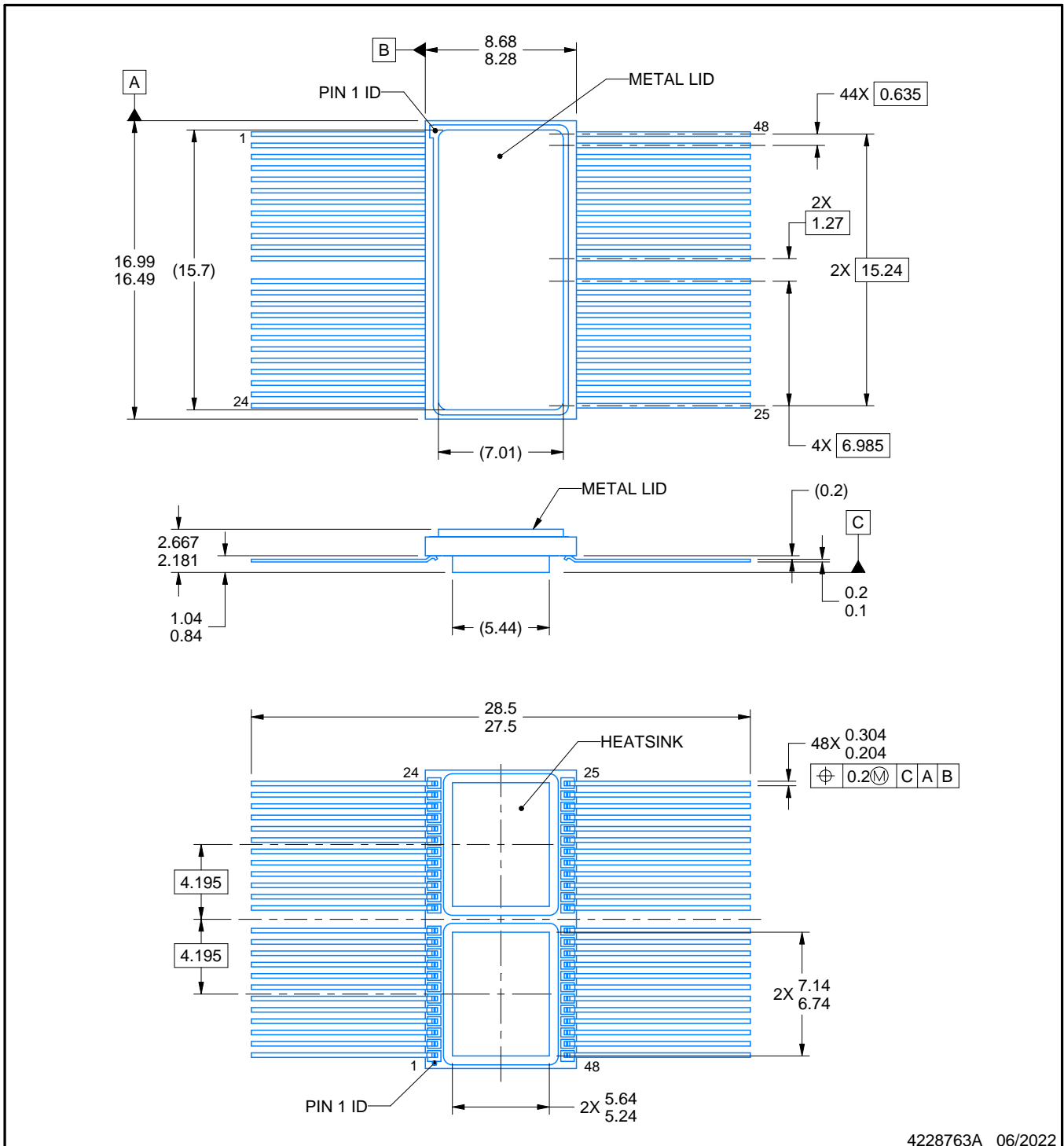


# HBX0048A

# PACKAGE OUTLINE

## CFP - 2.667 mm max height

CERAMIC DUAL FLATPACK



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### NOTES:

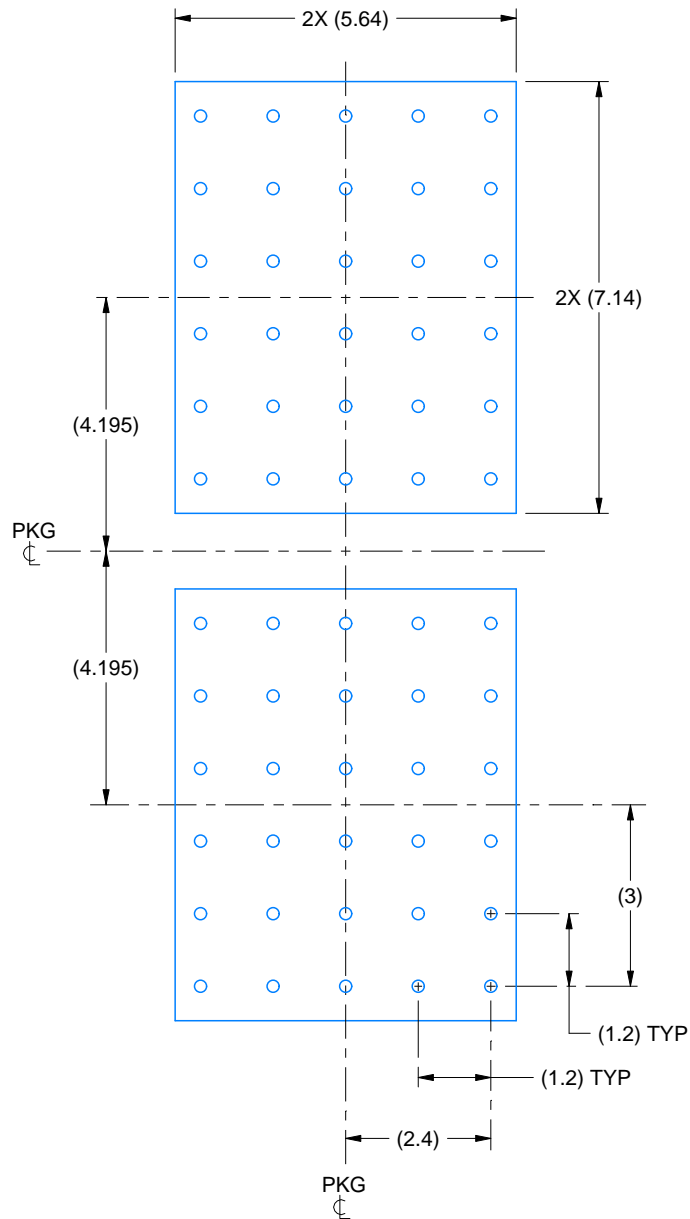
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a metal lid.
4. The terminals are gold plated.

# EXAMPLE BOARD LAYOUT

HBX0048A

CFP - 2.667 mm max height

CERAMIC DUAL FLATPACK



HEATSINK LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:8X

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